# SGM7229 High-Speed USB 2.0 (480Mbps) DPDT Analog Switch

#### **GENERAL DESCRIPTION**

The SGM7229 is a high-speed, low-power double-pole/double-throw (DPDT) analog switch that operates from a single 1.8V to 5.5V power supply.

The SGM7229 is designed for the switching of high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os.

The SGM7229 has low bit-to-bit skew and high channel-to-channel noise isolation, and is compatible with various standards, such as high-speed USB 2.0 (480Mbps). Each switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. Its bandwidth is wide enough to pass high-speed USB 2.0 differential signals (480Mbps) with good signal integrity.

The SGM7229 contains special circuitry on the D+/D-pins which allows the device to withstand a  $V_{\text{BUS}}$  short to D+ or D- when the USB devices are either powered off or powered on.

The SGM7229 is available in Green MSOP-10 and UTQFN-1.8×1.4-10L packages. It operates over an ambient temperature range of -40°C to +85°C.

#### **FEATURES**

Supply Voltage Range: 1.8V to 5.5V

• On-Resistance: 6Ω (TYP) at 3V

• Fast Switching Times at 3.3V:

 $t_{ON} = 30$ ns  $t_{OFF} = 18$ ns

• Crosstalk: -20dB at 250MHz

• Off-Isolation: -26dB at 250MHz

• Rail-to-Rail Input and Output Operation

• Break-Before-Make Switching

• -40°C to +85°C Operating Temperature Range

 Available in Green UTQFN-1.8×1.4-10L and MSOP-10 Packages

### **APPLICATIONS**

Route Signals for USB 2.0
MP3 and Other Personal Media Players
Digital Cameras and Camcorders
Portable Instrumentation
Set-Top Box
PDAs

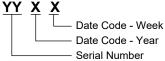
#### PACKAGE/ORDERING INFORMATION

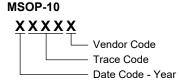
MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
CCM7220	UTQFN-1.8×1.4-10L	-40°C to +85°C	SGM7229YUWQ10G/TR	NDXX	Tape and Reel, 3000
SGM7229	MSOP-10	-40°C to +85°C	SGM7229YMS10G/TR	SGM7229 YMS10 XXXXX	Tape and Reel, 4000

#### MARKING INFORMATION

NOTE: XX = Date Code. XXXXX = Date Code, Trace Code and Vendor Code.

UTQFN-1.8×1.4-10L





Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

#### ABSOLUTE MAXIMUM RATINGS

V <sub>CC</sub> to GND	0V to 6V
Analog, Digital Voltage Range	0.3V to $V_{CC}$ + 0.3V
Continuous Current HSDn or Dn	±50mA
Peak Current HSDn or Dn	±100mA
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (Soldering, 10s)	+260°C
ESD Susceptibility	
HBM	2500V
MM	400V
CDM	1000V

#### RECOMMENDED OPERATING CONDITIONS

Operating Temperature Range .....-40°C to +85°C

#### **OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

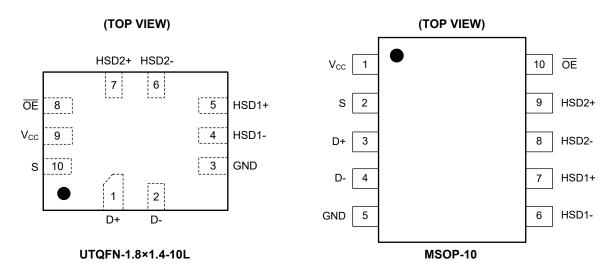
#### **ESD SENSITIVITY CAUTION**

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### **DISCLAIMER**

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

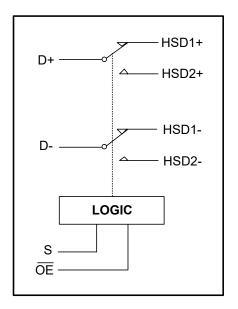
# **PIN CONFIGURATIONS**



# **PIN DESCRIPTION**

PIN		NAME	FUNCTION		
UTQFN-1.8×1.4-10L	MSOP-10	NAME	FUNCTION		
1	3	D+	USB Data Bus.		
2	4	D-	USB Data Bus.		
3	5	GND	Ground.		
4	6	HSD1-	Multiplexed Source Input.		
5	7	HSD1+	Multiplexed Source Input.		
6	8	HSD2-	Multiplexed Source Input.		
7	9	HSD2+	Multiplexed Source Input.		
8	10	ŌĒ	Output Enable.		
9	1	V <sub>CC</sub>	Power Supply.		
10	2	S	Select Input.		

# **BLOCK DIAGRAM**



# **FUNCTION TABLE**

ŌE	S	HSD1+, HSD1-	HSD2+, HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	×	OFF	OFF

NOTE: Switches shown for logic "0" input.

# **ELECTRICAL CHARACTERISTICS**

( $V_{CC}$  = 3.3V, Full = -40°C to +85°C, typical values are at  $T_A$  = +25°C, unless otherwise noted.)

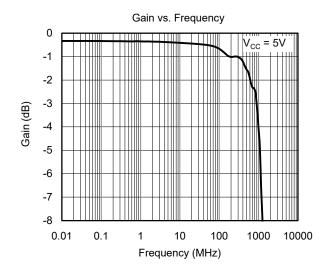
PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
ANALOG SWITCH							
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	V <sub>IS</sub>		Full	0		V <sub>CC</sub>	V
On-Resistance	R <sub>on</sub>	$V_{CC} = 3V$ , $V_{IS} = 0V$ to 0.4V,	+25°C		6	7	Ω
- Tresistance	· ON	I <sub>D</sub> = 8mA, Test Circuit 1	Full			8	
On-Resistance Match between Channels	$\Delta R_{ON}$	$V_{CC} = 3V$ , $V_{IS} = 0V$ to 0.4V,	+25°C		0.2	0.8	Ω
The state of the s	ZIVON	I <sub>D</sub> = 8mA, Test Circuit 1	Full			0.9	32
On-Resistance Flatness	R <sub>FLAT(ON)</sub>	$V_{CC} = 3V$ , $V_{IS} = 0V$ to 1V,	+25°C		2	3	Ω
On resistance ritations	TFLAT(ON)	I <sub>D</sub> = 8mA, Test Circuit 1	Full			3.5	32
Increase in I <sub>CC</sub> per Control Voltage	I <sub>CCT</sub>	$V_{CC} = 3.6V$ , $V_S$ or $V_{\overline{OE}} = 1.8V$	+25°C		2	3	μA
miorease in ice per control voltage	1001		Full			3.5	μ/ (
Power Off Leakage Current (D+, D-)	I <sub>OFF</sub>	$V_{CC} = 0V, V_D = 0V \text{ to } 3.6V, V_S, V_{\overline{OE}} = 0V \text{ or } 3.6V$	Full			0.5	μΑ
Source Off Leakage Current	I <sub>HSD2(OFF)</sub> , I <sub>HSD1(OFF)</sub>	$V_{CC} = 3.6V, V_{IS} = 3.3V/0.3V, V_{D} = 0.3V/3.3V$	Full			0.5	μΑ
Channel On Leakage Current	I <sub>HSD2(ON)</sub> , I <sub>HSD1(ON)</sub>	$V_{CC} = 3.6V, V_{IS} = 3.3V/0.3V,$ $V_{D} = 3.3V/0.3V$ or floating	Full			0.5	μA
DIGITAL INPUTS							
Input High Voltage	V <sub>IH</sub>		Full	1.5			V
Input Low Voltage	V <sub>IL</sub>		Full			0.4	V
Input Leakage Current	I <sub>IN</sub>	$V_S$ , $V_{\overline{OE}} = 0V$ or $V_{CC}$	Full			0.5	μA
DYNAMIC CHARACTERISTICS							
Turn-On Time	t <sub>ON</sub>	$V_{IS} = 0.8V, R_L = 50\Omega,$	+25°C		30		ns
Turn-Off Time	t <sub>OFF</sub>	C <sub>L</sub> = 10pF, Test Circuit 2	+25°C		18		ns
Break-Before-Make Time Delay	t <sub>D</sub>	$V_{IS}$ = 0.8V, $R_L$ = 50 $\Omega$ , $C_L$ = 10pF, Test Circuit 3	+25°C		14		ns
Propagation Delay	t <sub>PD</sub>	$R_L = 50\Omega, C_L = 10pF$	+25°C		0.5		ns
Off Isolation	O <sub>ISO</sub>	Signal = 0dBm, $R_L$ = 50 $\Omega$ , f = 250MHz, Test Circuit 4	+25°C		-26		dB
Channel-to-Channel Crosstalk	X <sub>TALK</sub>	Signal = 0dBm, R <sub>L</sub> = 50Ω, f = 250MHz, Test Circuit 5	+25°C		-20		dB
-3dB Bandwidth	BW	Signal = 0dBm, $R_L$ = 50 $\Omega$ , $C_L$ = 5pF, Test Circuit 6	+25°C		850		MHz
Channel-to-Channel Skew	t <sub>SKEW</sub>	$R_L = 50\Omega, C_L = 10pF$	+25°C		0.5		ns
Charge Injection Select Input to Common I/O	Q	$V_G = GND, C_L = 1nF, R_G = 0\Omega,$ $Q = C_L \times V_{OUT}, Test Circuit 7$	+25°C		2.5		рС
HSD+, HSD-, D+, D- On-Capacitance	Con	f = 1MHz	+25°C		8		pF

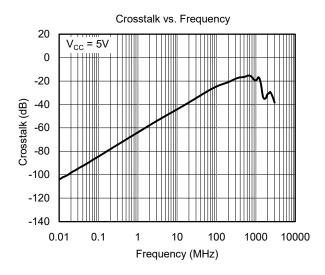
# **ELECTRICAL CHARACTERISTICS (continued)**

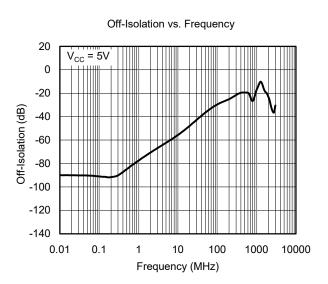
( $V_{CC}$  = 5V, Full = -40°C to +85°C, typical values are at  $T_A$  = +25°C, unless otherwise noted.)

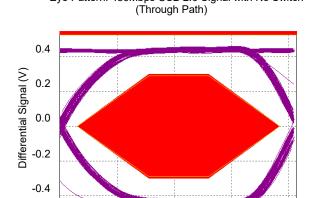
PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
ANALOG SWITCH							
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	V <sub>IS</sub>		Full	0		Vcc	V
((1301+, 11301-, 11302+, 11302-)		V <sub>IS</sub> = 0V to 0.4V,	+25°C		4.5	5.5	
On-Resistance	R <sub>on</sub>	$I_D = 8\text{mA}$ , Test Circuit 1	Full		1.0	6.5	Ω
		V <sub>IS</sub> = 0V to 0.4V,	+25°C		0.2	0.8	
On-Resistance Match between Channels	$\Delta R_{ON}$	I <sub>D</sub> = 8mA, Test Circuit 1	Full			0.9	Ω
On Business Flaterers	_	$V_{IS} = 0V \text{ to } 1V,$	+25°C		0.5	0.75	
On-Resistance Flatness	R <sub>FLAT(ON)</sub>	I <sub>D</sub> = 8mA, Test Circuit 1	Full			0.9	Ω
Increase in I <sub>CC</sub> per Control Voltage	_	$V_{CC} = 5.5V, V_{S} \text{ or } V_{\overline{OE}} = 1.8V$	+25°C		14	18	μA
Increase in icc per Control Voltage	I <sub>CCT</sub>	1	Full			22	μΑ
Power Off Leakage Current (D+, D-)	I <sub>OFF</sub>	$V_{CC} = 0V, V_D = 0V \text{ to } 5.5V, V_S, V_{\overline{OE}} = 0V \text{ or } 5.5V$	Full			0.5	μA
Source Off Leakage Current	I <sub>HSD2(OFF)</sub> , I <sub>HSD1(OFF)</sub>	$V_{CC} = 5.5V$ , $V_{IS} = 4.5V/1V$ , $V_{D} = 1V/4.5V$	Full			0.5	μΑ
Channel On Leakage Current	I <sub>HSD2(ON)</sub> , I <sub>HSD1(ON)</sub>	$V_{CC} = 5.5V$ , $V_{IS} = 4.5V/1V$ , $V_{D} = 4.5V/1V$ or floating	Full			0.5	μΑ
DIGITAL INPUTS	1105 (611)	, , , , ,					1
Input High Voltage	V <sub>IH</sub>	V <sub>CC</sub> = 5.5V	Full	1.8			V
Input Low Voltage	V <sub>IL</sub>	V <sub>CC</sub> = 5.5V	Full			0.6	V
Input Leakage Current	I <sub>IN</sub>	$V_{CC} = 5.5V$ , $V_{S}$ , $V_{\overline{QE}} = 0V$ or $V_{CC}$	Full			0.5	μA
DYNAMIC CHARACTERISTICS							•
Turn-On Time	On Time $t_{ON}$ $V_{IS} = 0.8$		+25°C		22		ns
Turn-Off Time	t <sub>OFF</sub>	C <sub>L</sub> = 10pF, Test Circuit 2	+25°C		14		ns
Break-Before-Make Time Delay	t <sub>D</sub>	$V_{IS} = 0.8V$ , $R_L = 50\Omega$ , $C_L = 10pF$ , Test Circuit 3	+25°C		9		ns
Propagation Delay	t <sub>PD</sub>	$R_L = 50\Omega$ , $C_L = 10pF$	+25°C		0.5		ns
Off Isolation	O <sub>ISO</sub>	Signal = 0dBm, $R_L$ = $50\Omega$ , f = 250MHz, Test Circuit 4	+25°C		-26		dB
Channel-to-Channel Crosstalk	X <sub>TALK</sub>	Signal = 0dBm, $R_L$ = 50 $\Omega$ , f = 250MHz, Test Circuit 5	+25°C		-20		dB
-3dB Bandwidth	BW	Signal = 0dBm, $R_L$ = 50 $\Omega$ , $C_L$ = 5pF, Test Circuit 6	+25°C		850		MHz
Channel-to-Channel Skew	t <sub>SKEW</sub>	$R_L = 50\Omega$ , $C_L = 10pF$	+25°C		0.5		ns
Charge Injection Select Input to Common I/O	Q	$V_G$ = GND, $C_L$ = 1nF, $R_G$ = 0 $\Omega$ , $Q$ = $C_L$ × $V_{OUT}$ , Test Circuit 7	+25°C		3.5		рС
HSD+, HSD-, D+, D- On-Capacitance	Con	f = 1MHz	+25°C		8		pF
POWER REQUIREMENTS							
Power Supply Range	V <sub>cc</sub>	_	Full	1.8		5.5	V
Power Supply Current	I <sub>cc</sub>	$V_{CC} = 5.5V$ , $V_{S}$ , $V_{\overline{OE}} = 0V$ or $V_{CC}$	Full			0.5	μΑ

# TYPICAL PERFORMANCE CHARACTERISTICS





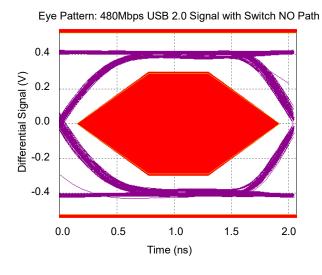


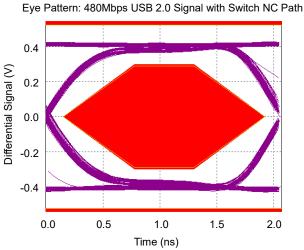


0.0

0.5

Eye Pattern: 480Mbps USB 2.0 Signal with No Switch





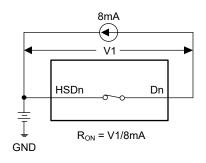
1.0

Time (ns)

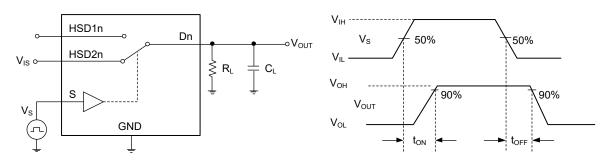
1.5

2.0

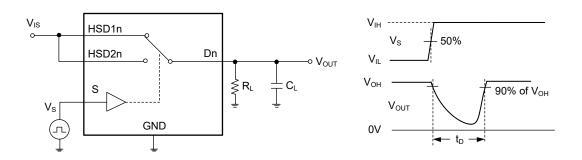
## **TEST CIRCUITS**



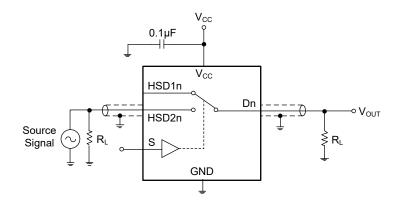
Test Circuit 1. On-Resistance



Test Circuit 2. Switching Times (ton, toff)

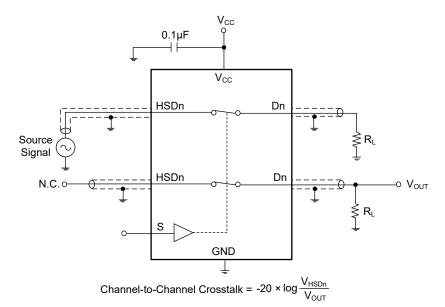


Test Circuit 3. Break-Before-Make Time Delay (t<sub>D</sub>)

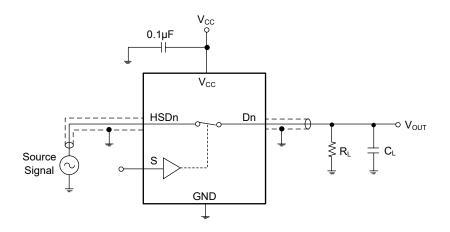


**Test Circuit 4. Off Isolation** 

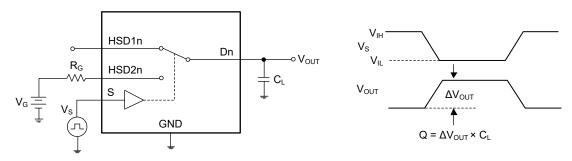
# **TEST CIRCUITS (continued)**



Test Circuit 5. Channel-to-Channel Crosstalk



Test Circuit 6. -3dB Bandwidth



Test Circuit 7. Charge Injection (Q)

## **APPLICATION NOTES**

# Meeting USB 2.0 V<sub>BUS</sub> Short Requirements Power-Off Protection

For a  $V_{\text{BUS}}$  short circuit, the switch is expected to withstand such a condition for at least 24 hours. The SGM7229 has specially designed circuitry which prevents unintended signal bleeding through as well as guarantees system reliability during a power-down, over-voltage condition. The protection has been added to the common pins (D+, D-).

#### **Power-On Protection**

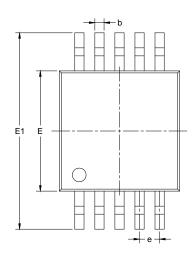
The USB 2.0 specification also notes that the USB device should be capable of withstanding a  $V_{\text{BUS}}$  short during transmission of data. This modification works by limiting current flow back into the  $V_{\text{CC}}$  rail during the over-voltage event so current remains within the safe operating range.

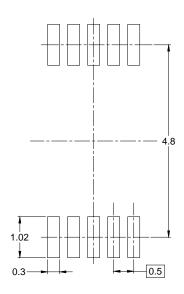
#### **REVISION HISTORY**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

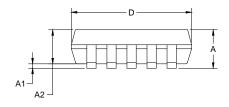
December 2021 – REV.A to REV.B	Page
Updated Electrical Characteristics section	5, 6
Changes from Original (DECEMBER 2018) to REV.A	
Changed from product preview to production data	All

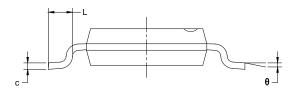
# **PACKAGE OUTLINE DIMENSIONS** MSOP-10





RECOMMENDED LAND PATTERN (Unit: mm)



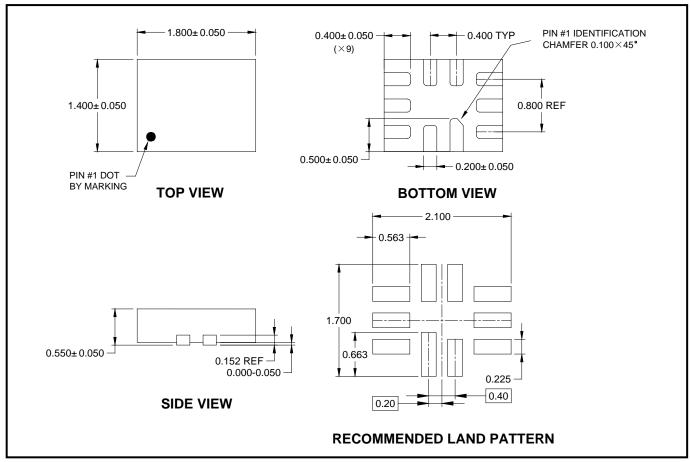


Symbol		nsions meters	Dimensions In Inches		
,	MIN	MAX	MIN	MAX	
Α	0.820	1.100	0.032	0.043	
A1	0.020	0.150	0.001	0.006	
A2	0.750	0.950	0.030	0.037	
b	0.180	0.280	0.007	0.011	
С	0.090	0.230	0.004	0.009	
D	2.900	3.100	0.114	0.122	
E	2.900	3.100	0.114	0.122	
E1	4.750	5.050	0.187	0.199	
е	0.500	0.500 BSC		BSC	
L	0.400	0.800	0.016	0.031	
θ	0°	6°	0°	6°	

#### NOTES:

- Body dimensions do not include mode flash or protrusion.
   This drawing is subject to change without notice.

# PACKAGE OUTLINE DIMENSIONS UTQFN-1.8×1.4-10L

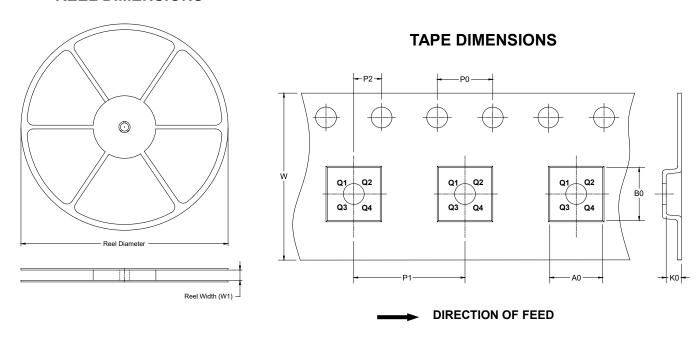


#### NOTES:

- 1. All linear dimensions are in millimeters.
- 2. This drawing is subject to change without notice.

# TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**



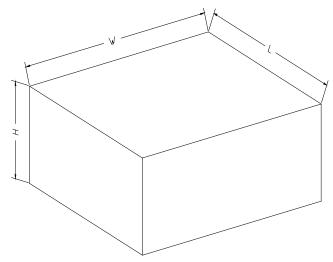
NOTE: The picture is only for reference. Please make the object as the standard.

#### **KEY PARAMETER LIST OF TAPE AND REEL**

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
UTQFN-1.8×1.4-10L	7"	9.0	1.75	2.10	0.70	4.0	4.0	2.0	8.0	Q1
MSOP-10	13"	12.4	5.20	3.30	1.20	4.0	8.0	2.0	12.0	Q1

DD0001

## **CARTON BOX DIMENSIONS**



NOTE: The picture is only for reference. Please make the object as the standard.

### **KEY PARAMETER LIST OF CARTON BOX**

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18
13"	386	280	370	5